

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In the Claims.

16  
36. (Amended) A method, comprising the steps of:

5        depositing first conductive film over a first insulating layer having a hole  
formed therein, the first conductive film being thicker over a top surface of the  
first insulating layer than on a side surface of the hole;

      depositing a second conductive film over the first conductive film;

      depositing a third conductive film over the second conductive film and  
within the hole;

10        etching the third conductive film selective to the second conductive film to  
expose the second conductive film around the hole, the third conductive film  
being only within the hole and having a plug top that extends above the top  
surface of the first insulating layer but below a top surface of the second  
conductive film; and

15        selectively etching the first and second conductive films relative to the  
third conductive film to expose the top surface of the first insulating film around  
the hole, the first and second conductive films being only within the hole.

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Please cancel claim 37.